

<b>PATENT ASSIGNMENT COVER SHEET</b>
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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
DONGQI LIU	11/19/2020
HAO YI	11/19/2020
WEIDONG ZHANG	11/19/2020
RUNHONG LIU	11/19/2020
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<b>Street Address:</b>	ROOM 133-134, PRODUCTIVITY BUILDING, SONGSHAN LAKE HIGH-TECH ZONE,
<b>City:</b>	DONGGUAN, GUANGDONG
<b>State/Country:</b>	CHINA
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16952106
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<b>Fax Number:</b>	
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<b>NAME OF SUBMITTER:</b>	MIKE LI
<b>SIGNATURE:</b>	/Mike Li/
<b>DATE SIGNED:</b>	11/19/2020
This document serves as an Oath/Declaration (37 CFR 1.63).	
<b>Total Attachments: 2</b>	
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## ASSIGNMENT

WHEREAS, We, whose addresses appear below, hereinafter referred to as ASSIGNORS, have invented new and useful improvements in Foam molding process by modifying amorphous PLA (hereinafter referred to as the INVENTION) for which an application for the United States Letters Patent was

filed on: 11/19/2020

Application Number: **16/952,106**

WHEREAS, Dongguan Hailex New Material Science and Technology Co., Ltd. whose address is 8, Renhuagong 3<sup>rd</sup> Road, Longgang District, Dongguan, Guangdong, China hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States.

ASSIGNORS, hereby authorize and request the Commissioner for Patents and Trademarks to issue any and all United States Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for the ASSIGNEE's sole use and behoof, and for the use and behoof of ASSIGNEE's legal representatives and successors, to the full end of the term for which such LETTERS PATENT may be granted, as fully and entirely as the same would have been held by ASSIGNORS has this assignment and sale not been made.

Assignor: Dongqi Liu

Address: 8, Renhuagong 3<sup>rd</sup> Road, Longgang District, Dongguan, Guangdong, China

Date: 11/19/2020

Signature: /Dongqi Liu/

Assignor: Hao Yi

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Date: 11/19/2020

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Date: 11/19/2020

Signature: /Runhong Liu/